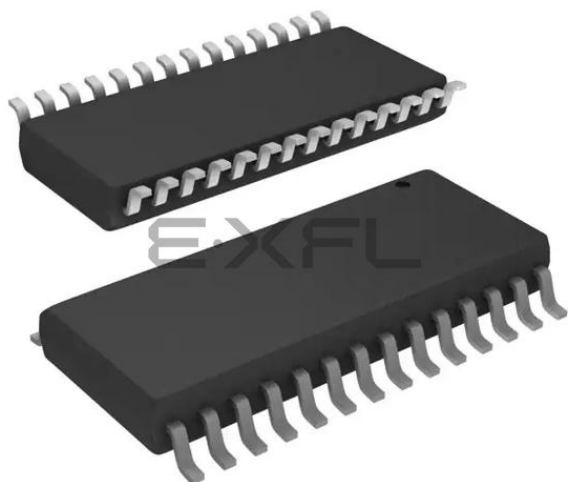




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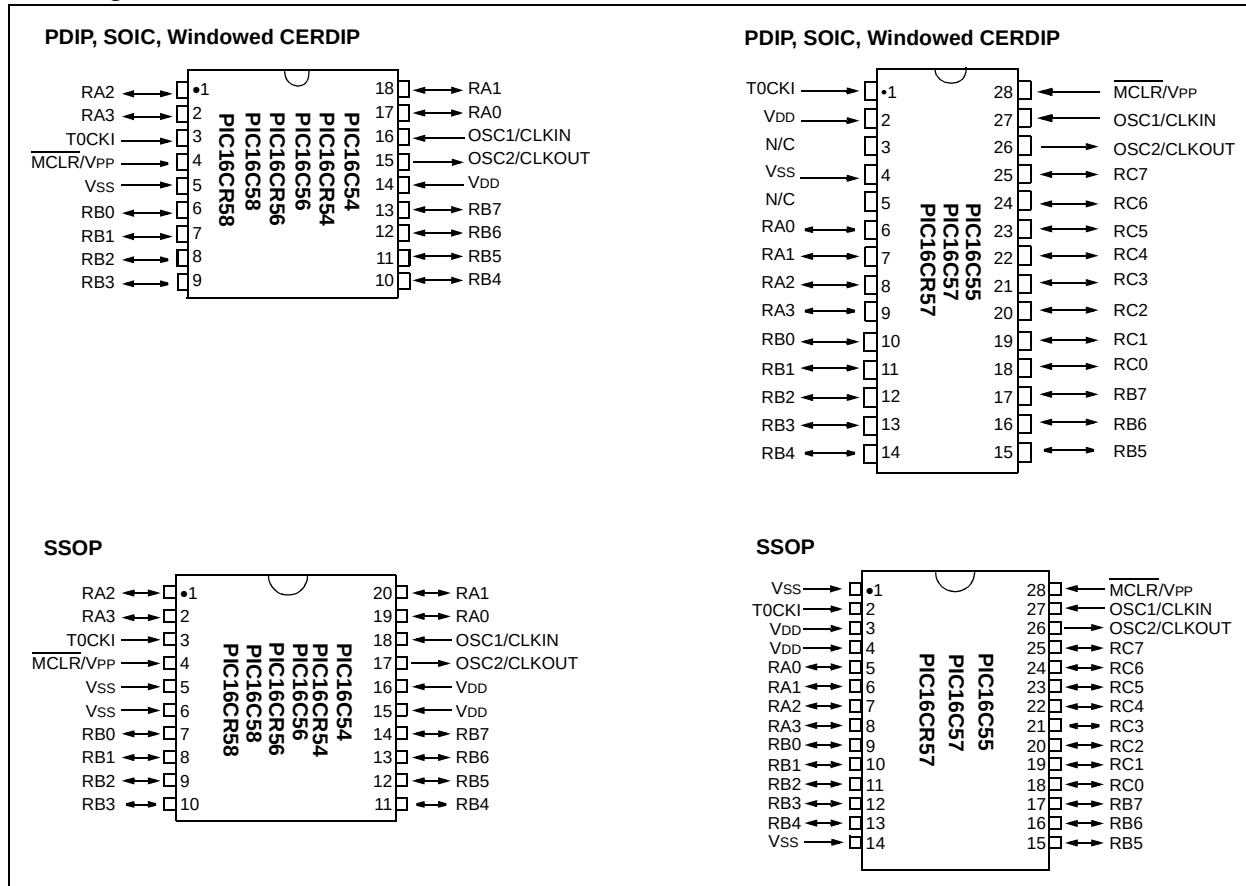
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	24 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c55-lp-so

PIC16C5X

Pin Diagrams



Device Differences

Device	Voltage Range	Oscillator Selection (Program)	Oscillator	Process Technology (Microns)	ROM Equivalent	MCLR Filter
PIC16C54	2.5-6.25	Factory	See Note 1	1.2	PIC16CR54A	No
PIC16C54A	2.0-6.25	User	See Note 1	0.9	—	No
PIC16C54C	2.5-5.5	User	See Note 1	0.7	PIC16CR54C	Yes
PIC16C55	2.5-6.25	Factory	See Note 1	1.7	—	No
PIC16C55A	2.5-5.5	User	See Note 1	0.7	—	Yes
PIC16C56	2.5-6.25	Factory	See Note 1	1.7	—	No
PIC16C56A	2.5-5.5	User	See Note 1	0.7	PIC16CR56A	Yes
PIC16C57	2.5-6.25	Factory	See Note 1	1.2	—	No
PIC16C57C	2.5-5.5	User	See Note 1	0.7	PIC16CR57C	Yes
PIC16C58B	2.5-5.5	User	See Note 1	0.7	PIC16CR58B	Yes
PIC16CR54A	2.5-6.25	Factory	See Note 1	1.2	N/A	Yes
PIC16CR54C	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes
PIC16CR56A	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes
PIC16CR57C	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes
PIC16CR58B	2.5-5.5	Factory	See Note 1	0.7	N/A	Yes

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

Note: The table shown above shows the generic names of the PIC16C5X devices. For device varieties, please refer to Section 2.0.

4.3 External Crystal Oscillator Circuit

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 4-3 shows an implementation example of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 4-3: EXAMPLE OF EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)

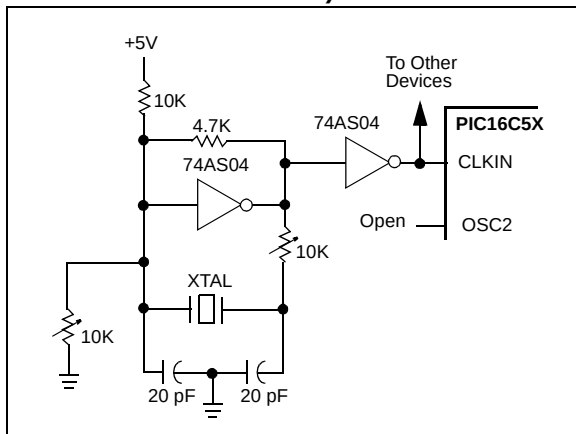
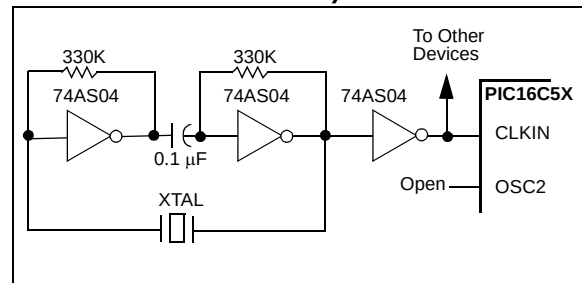


Figure 4-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 k Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 4-4: EXAMPLE OF EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)



PIC16C5X

NOTES:

8.0 TIMER0 MODULE AND TMR0 REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
 - Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
 - Edge select for external clock

Figure 8-1 is a simplified block diagram of the Timer0 module, while Figure 8-2 shows the electrical structure of the Timer0 input.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two cycles (Figure 8-3 and Figure 8-4). The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The incrementing edge is determined by the source edge select bit T0SE (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 8.1.

Note: The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both.

The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 8.2 details the operation of the prescaler.

A summary of registers associated with the Timer0 module is found in Table 8-1.

FIGURE 8-1: TIMER0 BLOCK DIAGRAM

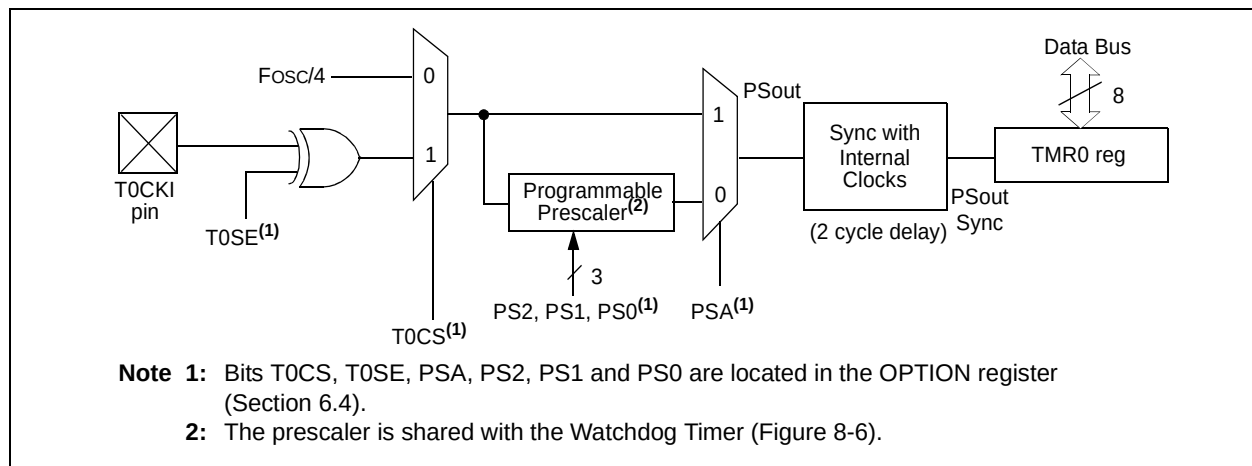
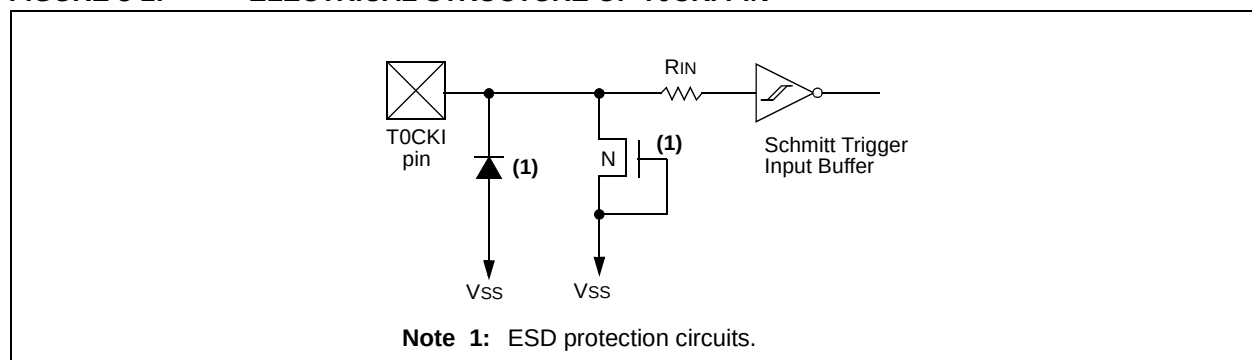


FIGURE 8-2: ELECTRICAL STRUCTURE OF T0CKI PIN



11.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can also link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian is a librarian for pre-compiled code to be used with the MPLINK object linker. When a routine from a library is called from another source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. The MPLIB object librarian manages the creation and modification of library files.

The MPLINK object linker features include:

- Integration with MPASM assembler and MPLAB C17 and MPLAB C18 C compilers.
- Allows all memory areas to be defined as sections to provide link-time flexibility.

The MPLIB object librarian features include:

- Easier linking because single libraries can be included instead of many smaller files.
- Helps keep code maintainable by grouping related modules together.
- Allows libraries to be created and modules to be added, listed, replaced, deleted or extracted.

11.5 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC-hosted environment by simulating the PIC series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user-defined key press, to any of the pins. The execution can be performed in single step, execute until break, or trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and the MPLAB C18 C compilers and the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent multi-project software development tool.

11.6 MPLAB ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB ICE universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC microcontrollers (MCUs). Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE in-circuit emulator system has been designed as a real-time emulation system, with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows environment were chosen to best make these features available to you, the end user.

11.7 ICEPIC In-Circuit Emulator

The ICEPIC low cost, in-circuit emulator is a solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X and PIC16CXXX families of 8-bit One-Time-Programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules, or daughter boards. The emulator is capable of emulating without target application circuitry being present.

PIC16C5X

12.3 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage PIC16C5X-RCE PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-LPE	3.25 3.25 4.5 4.5 2.5	— — — — —	6.0 6.0 5.5 5.5 6.0	V V V V V	
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RCE ⁽³⁾ PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-HSE PIC16C5X-LPE	— — — — — —	1.8 1.8 4.8 4.8 9.0 19	3.3 3.3 10 10 20 55	mA mA mA mA mA μA	FOSC = 4 MHz, VDD = 5.5V FOSC = 4 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 16 MHz, VDD = 5.5V FOSC = 32 kHz, VDD = 3.25V, WDT disabled
D020	IPD	Power-down Current ⁽²⁾	— —	5.0 0.8	22 18	μA μA	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

PIC16C5X

12.7 Timing Diagrams and Specifications

FIGURE 12-2: EXTERNAL CLOCK TIMING - PIC16C54/55/56/57

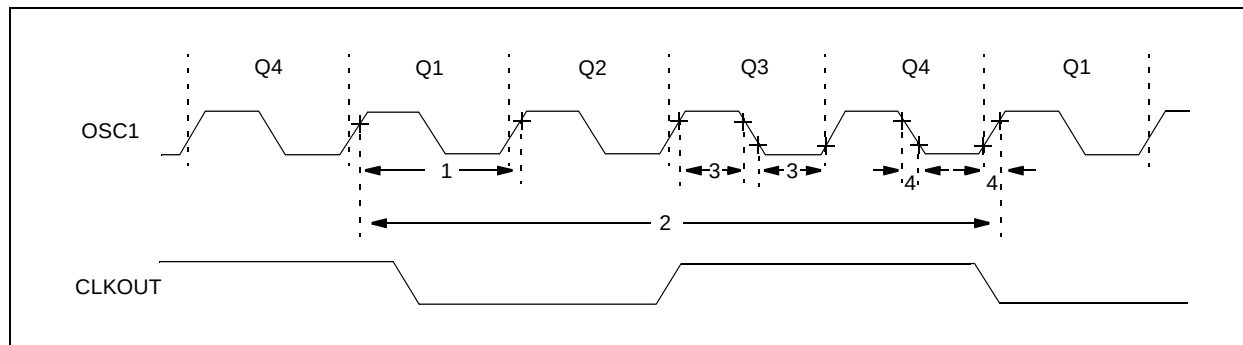


TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics		Operating Temperature					
		0°C ≤ TA ≤ +70°C for commercial					
		-40°C ≤ TA ≤ +85°C for industrial					
		-40°C ≤ TA ≤ +125°C for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency ⁽¹⁾	DC	—	4.0	MHz	XT osc mode
			DC	—	10	MHz	10 MHz mode
			DC	—	20	MHz	HS osc mode (Comm/Ind)
			DC	—	16	MHz	HS osc mode (Ext)
			DC	—	40	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	—	4.0	MHz	RC osc mode
			0.1	—	4.0	MHz	XT osc mode
			4.0	—	10	MHz	10 MHz mode
			4.0	—	20	MHz	HS osc mode (Comm/Ind)
			4.0	—	16	MHz	HS osc mode (Ext)
			DC	—	40	kHz	LP osc mode

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (Tcy) equals four times the input oscillator time base period.

13.0 ELECTRICAL CHARACTERISTICS - PIC16CR54A

Absolute Maximum Ratings^(†)

Ambient Temperature under bias	–55°C to +125°C
Storage Temperature	–65°C to +150°C
Voltage on V _{DD} with respect to V _{SS}	0 to +7.5V
Voltage on MCLR with respect to V _{SS} ⁽¹⁾	0 to +14V
Voltage on all other pins with respect to V _{SS}	–0.6V to (V _{DD} + 0.6V)
Total power dissipation ⁽²⁾	800 mW
Max. current out of V _{SS} pin	150 mA
Max. current into V _{DD} pin	50 mA
Max. current into an input pin (TOCKI only)	±500 µA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O port (PORTA or B)	40 mA
Max. output current sunk by a single I/O port (PORTA or B)	50 mA

Note 1: Voltage spikes below V_{SS} at the MCLR pin, inducing currents greater than 80 mA may cause latch-up. Thus, a series resistor of 50 to 100 Ω should be used when applying a low level to the MCLR pin rather than pulling this pin directly to V_{SS}.

2: Power Dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LCR54A-04 PIC16LCR54A-04I (Commercial, Industrial)			Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial				
PIC16CR54A-04, 10, 20 PIC16CR54A-04I, 10I, 20I (Commercial, Industrial)			Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial				
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
	IPD	Power-down Current⁽²⁾					
D006		PIC16LCR54A-Commercial	—	1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μA μA μA μA	$V_{DD} = 2.5\text{V}$, WDT disabled $V_{DD} = 4.0\text{V}$, WDT disabled $V_{DD} = 6.0\text{V}$, WDT disabled $V_{DD} = 6.0\text{V}$, WDT enabled
D006A		PIC16CR54A-Commercial	—	1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μA μA μA μA	$V_{DD} = 2.5\text{V}$, WDT disabled $V_{DD} = 4.0\text{V}$, WDT disabled $V_{DD} = 6.0\text{V}$, WDT disabled $V_{DD} = 6.0\text{V}$, WDT enabled
D007		PIC16LCR54A-Industrial	—	1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μA μA μA μA μA	$V_{DD} = 2.5\text{V}$, WDT disabled $V_{DD} = 4.0\text{V}$, WDT disabled $V_{DD} = 4.0\text{V}$, WDT enabled $V_{DD} = 6.0\text{V}$, WDT disabled $V_{DD} = 6.0\text{V}$, WDT enabled
D007A		PIC16CR54A-Industrial	—	1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μA μA μA μA μA	$V_{DD} = 2.5\text{V}$, WDT disabled $V_{DD} = 4.0\text{V}$, WDT disabled $V_{DD} = 4.0\text{V}$, WDT enabled $V_{DD} = 6.0\text{V}$, WDT disabled $V_{DD} = 6.0\text{V}$, WDT enabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all I_{DD} measurements in active Operation mode are: $OSC1$ = external square wave, from rail-to-rail; all I/O pins tristated, pulled to V_{SS} , $T0CKI = V_{DD}$, $MCLR = V_{DD}$; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through R_{EXT} . The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in k Ω .

13.3 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial −40°C ≤ TA ≤ +85°C for industrial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	V _{IL}	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	V _{SS} V _{SS} V _{SS} V _{SS} V _{SS}	— — — — —	0.2 V _{DD} 0.15 V _{DD} 0.15 V _{DD} 0.15 V _{DD} 0.15 V _{DD}	V V V V V	Pin at hi-impedance RC mode only ⁽³⁾ XT, HS and LP modes
D040	V _{IH}	Input High Voltage I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	2.0 0.6 V _{DD} 0.85 V _{DD} 0.85 V _{DD} 0.85 V _{DD} 0.85 V _{DD}	— — — — — —	V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD}	V V V V V V	V _{DD} = 3.0V to 5.5V ⁽⁴⁾ Full V _{DD} range ⁽⁴⁾ RC mode only ⁽³⁾ XT, HS and LP modes
D050	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.15 V _{DD} *	—	—	V	
D060	I _{IL}	Input Leakage Current^(1,2) I/O ports MCLR MCLR T0CKI OSC1	−1.0 −5.0 — −3.0 −3.0	— — 0.5 0.5 0.5	+1.0 — +5.0 +3.0 +3.0	μA μA μA μA μA	For V_{DD} ≤ 5.5V: V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance V _{PIN} = V _{SS} + 0.25V V _{PIN} = V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP modes
D080	V _{OL}	Output Low Voltage I/O ports OSC2/CLKOUT	— —	— —	0.5 0.5	V V	I _{OL} = 10 mA, V _{DD} = 6.0V I _{OL} = 1.9 mA, V _{DD} = 6.0V, RC mode only
D090	V _{OH}	Output High Voltage⁽²⁾ I/O ports OSC2/CLKOUT	V _{DD} − 0.5 V _{DD} − 0.5	— —	— —	V V	I _{OH} = −4.0 mA, V _{DD} = 6.0V I _{OH} = −0.8 mA, V _{DD} = 6.0V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

TABLE 13-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A

Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1	Tosc	External CLKIN Period ⁽¹⁾	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (04)
			100	—	—	ns	HS osc mode (10)
			50	—	—	ns	HS osc mode (20)
			5.0	—	—	μs	LP osc mode
		Oscillator Period ⁽¹⁾	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (04)
			100	—	250	ns	HS osc mode (10)
			50	—	250	ns	HS osc mode (20)
			5.0	—	200	μs	LP osc mode
2	Tcy	Instruction Cycle Time ⁽²⁾	—	4/Fosc	—	—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	—	—	ns	XT oscillator
			20*	—	—	ns	HS oscillator
			2.0*	—	—	μs	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	25*	ns	XT oscillator
			—	—	25*	ns	HS oscillator
			—	—	50*	ns	LP oscillator

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (Tcy) equals four times the input oscillator time base period.

14.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

“Typical” represents the mean of the distribution at 25°C. “Maximum” or “minimum” represents (mean + 3 σ) or (mean – 3 σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 14-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

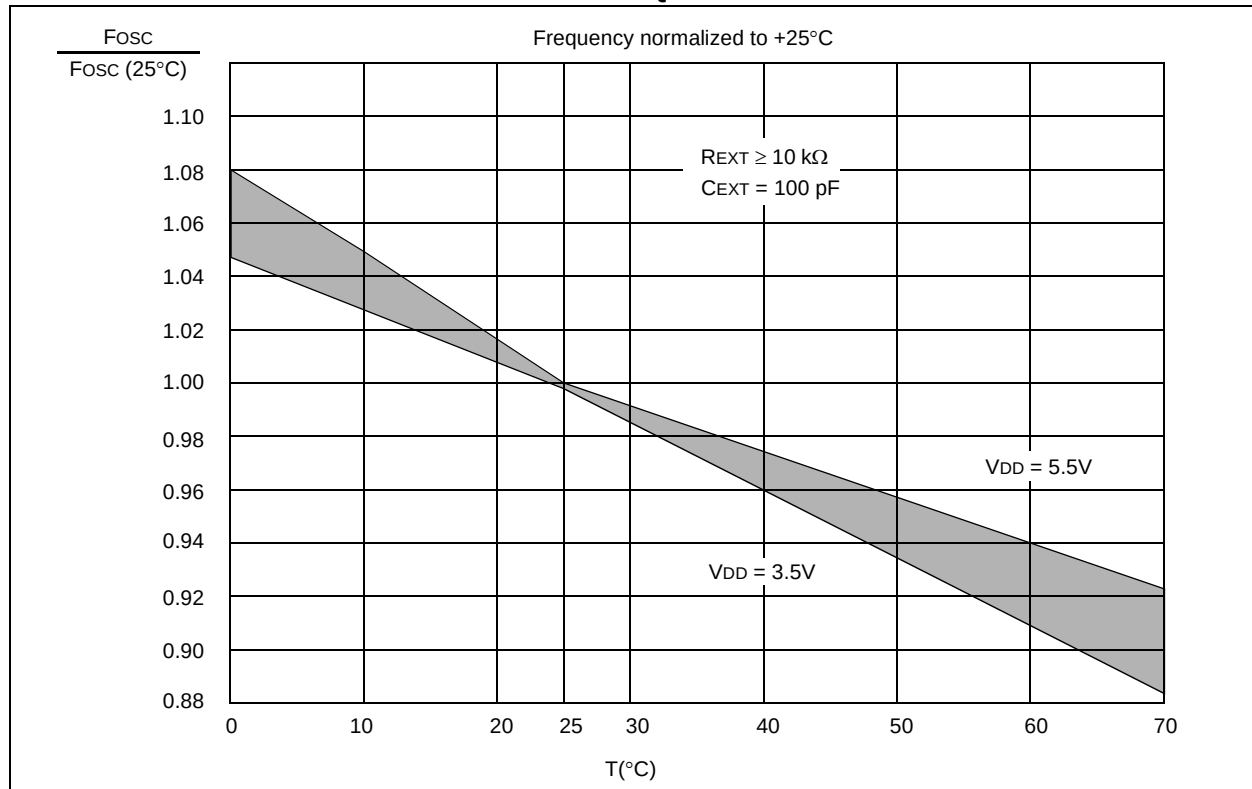


TABLE 14-1: RC OSCILLATOR FREQUENCIES

C_{EXT}	R_{EXT}	Average F_{osc} @ 5 V, 25°C	
20 pF	3.3K	5 MHz	± 27%
	5K	3.8 MHz	± 21%
	10K	2.2 MHz	± 21%
	100K	262 kHz	± 31%
100 pF	3.3K	1.6 MHz	± 13%
	5K	1.2 MHz	± 13%
	10K	684 kHz	± 18%
	100K	71 kHz	± 25%
300 pF	3.3K	660 kHz	± 10%
	5.0K	484 kHz	± 14%
	10K	267 kHz	± 15%
	100K	29 kHz	± 19%

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ± 3 standard deviations from the average value for $V_{DD} = 5\text{V}$.

FIGURE 14-9: V_{TH} (INPUT THRESHOLD VOLTAGE) OF I/O PINS vs. V_{DD}

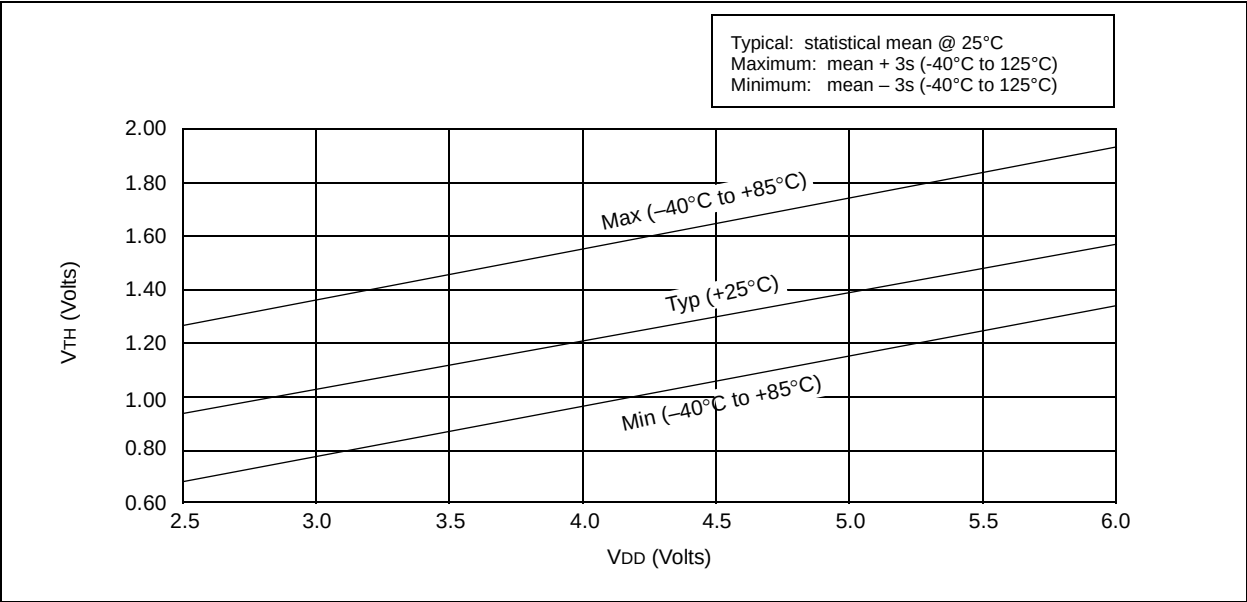
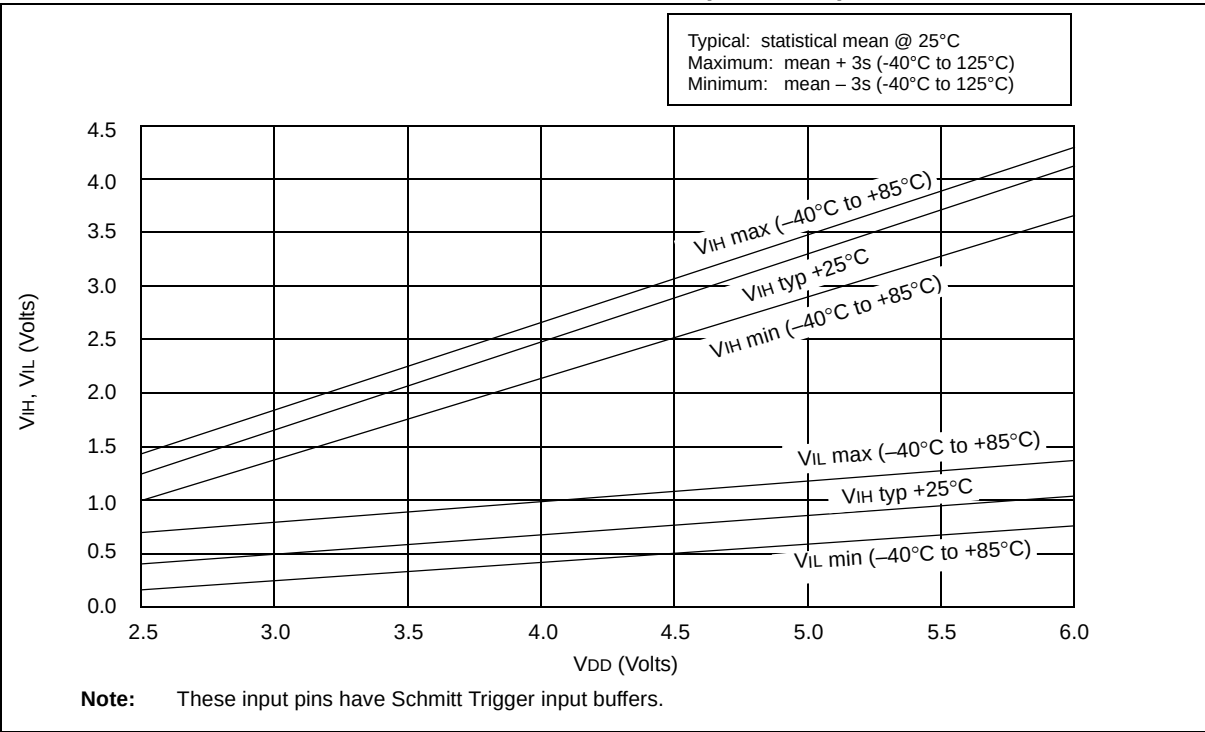


FIGURE 14-10: V_{IH} , V_{IL} OF MCLR, T0CKI AND OSC1 (RC MODE) vs. V_{DD}



PIC16C5X

FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY vs. V_{DD} , $C_{EXT} = 20\text{ pF}$, 25°C

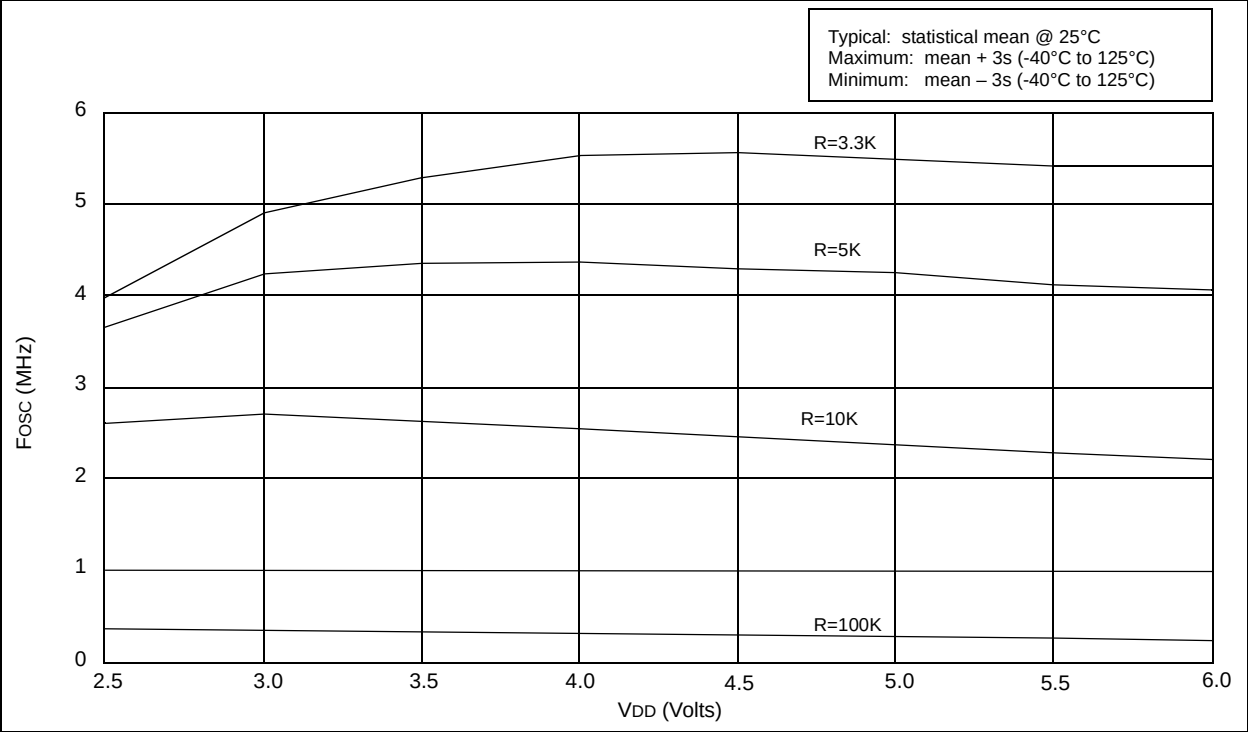
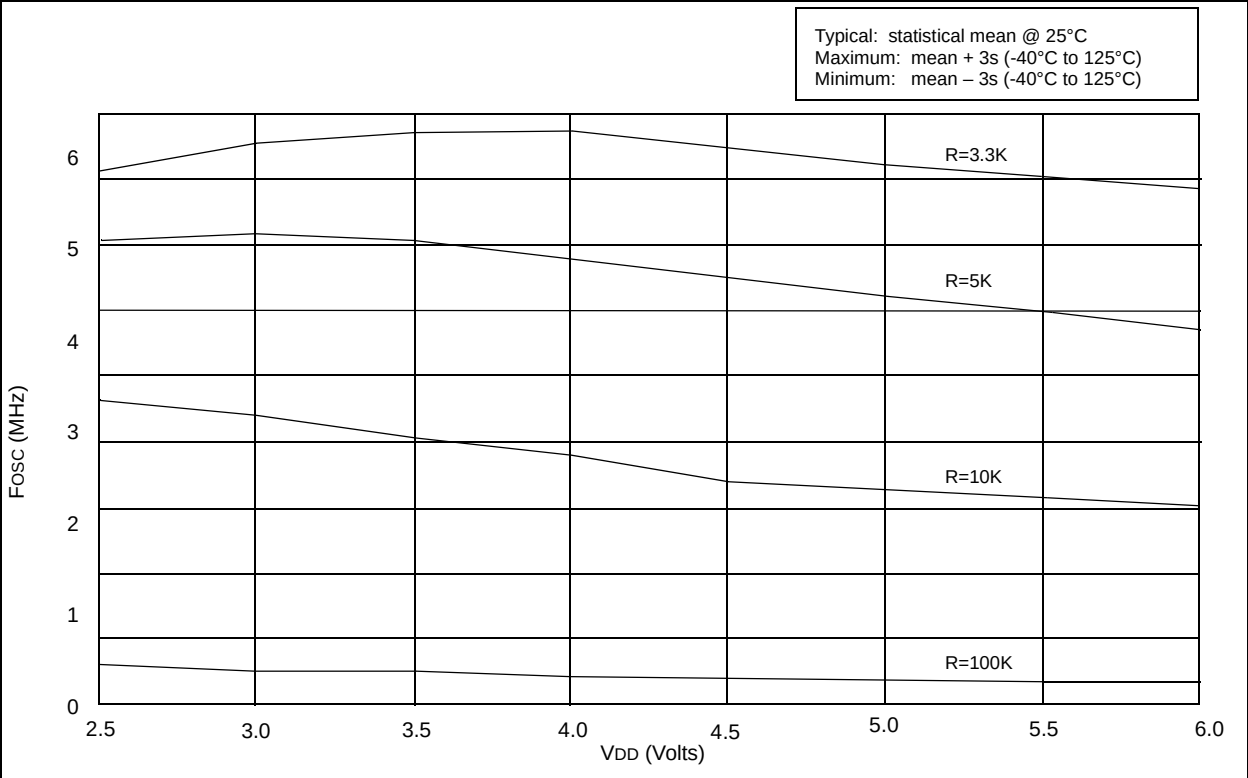
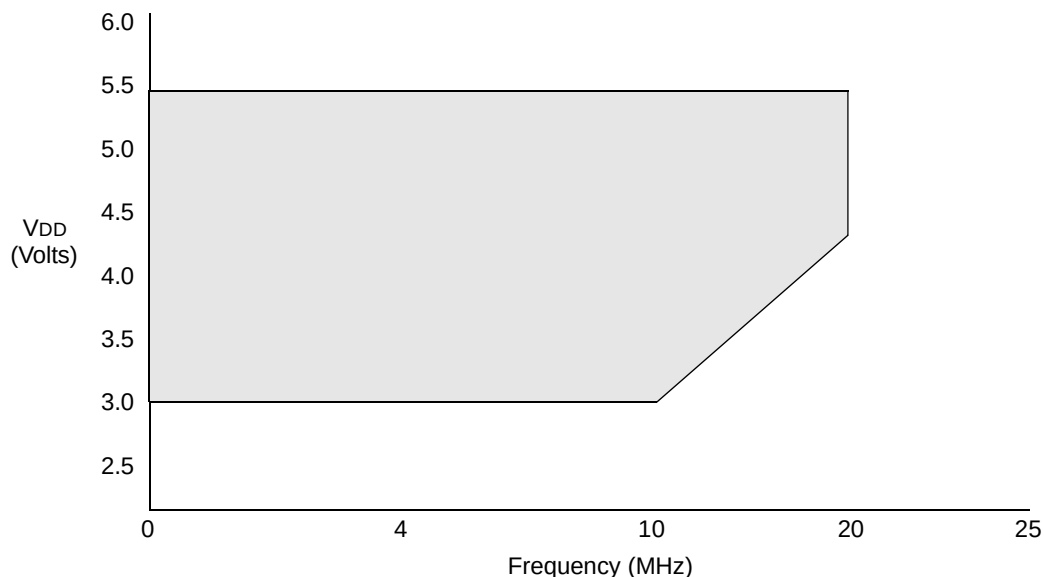


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY vs. V_{DD} , $C_{EXT} = 100\text{ pF}$, 25°C



PIC16C5X

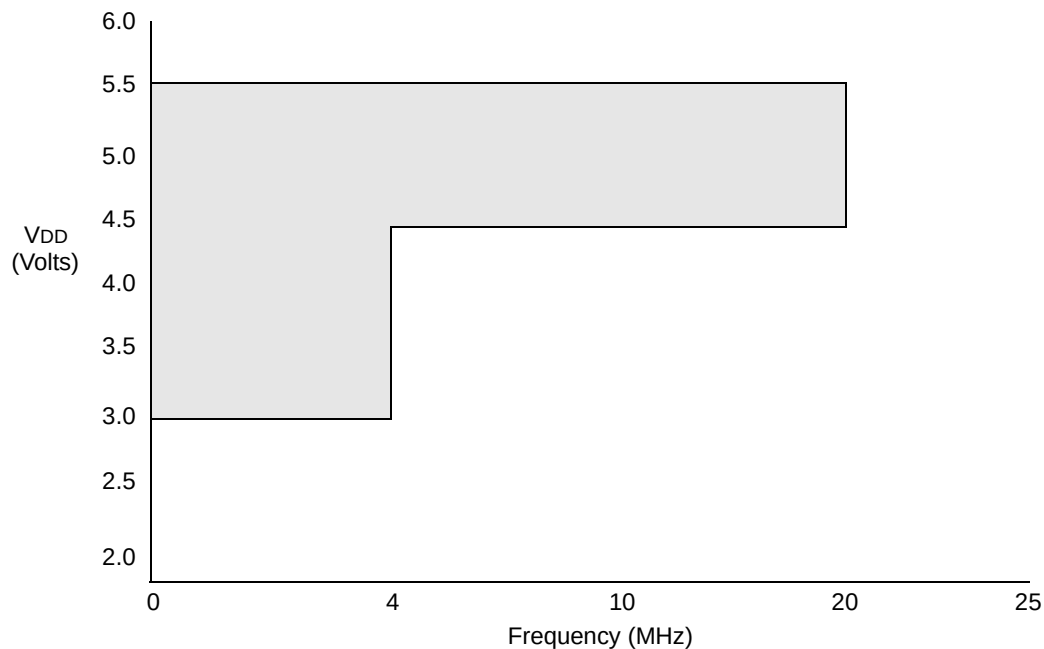
FIGURE 17-1: PIC16C54C/55A/56A/57C/58B-04, 20 VOLTAGE-FREQUENCY GRAPH, $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ (COMMERCIAL TEMPS)



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

Note 2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 17-2: PIC16C54C/55A/56A/57C/58B-04, 20 VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A < 0^{\circ}\text{C}$, $+70^{\circ}\text{C} < T_A \leq +125^{\circ}\text{C}$ (OUTSIDE OF COMMERCIAL TEMPS)



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

Note 2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 17-3: PIC16LC54C/55A/56A/57C/58B VOLTAGE-FREQUENCY GRAPH, $0^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$

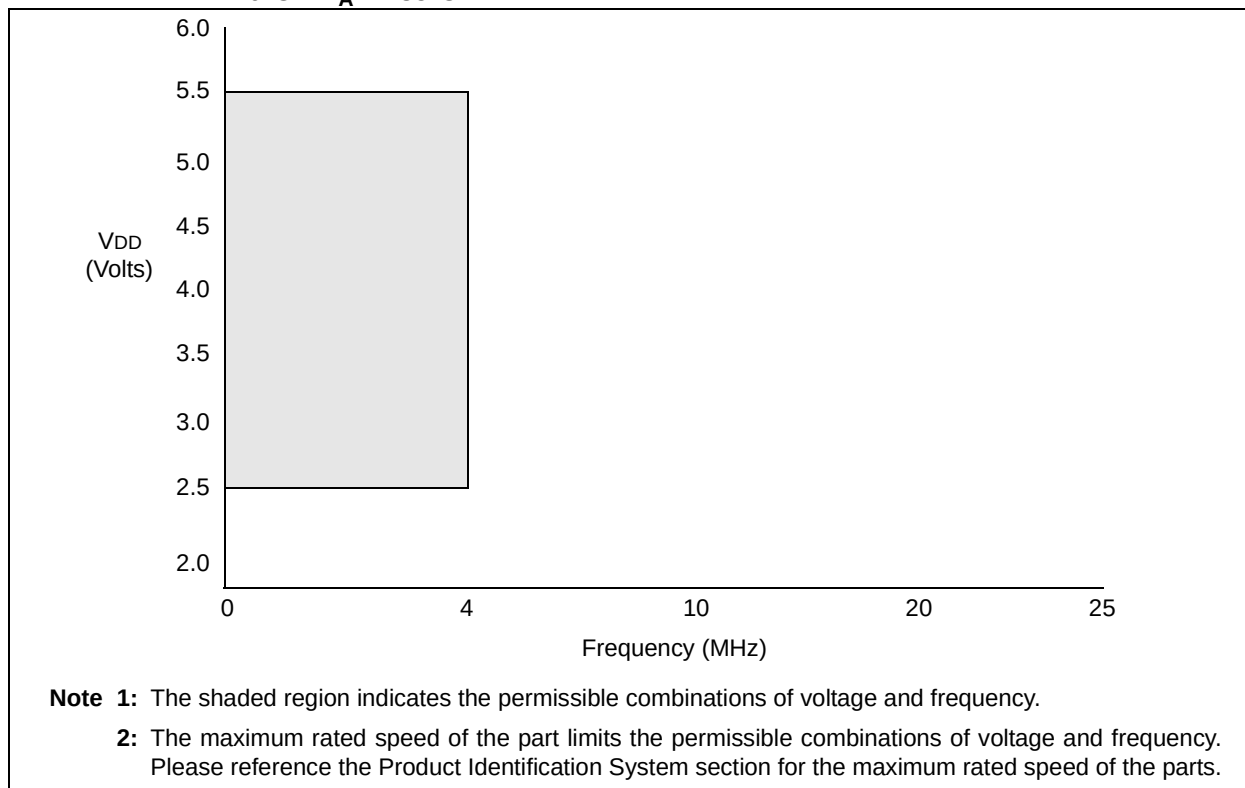
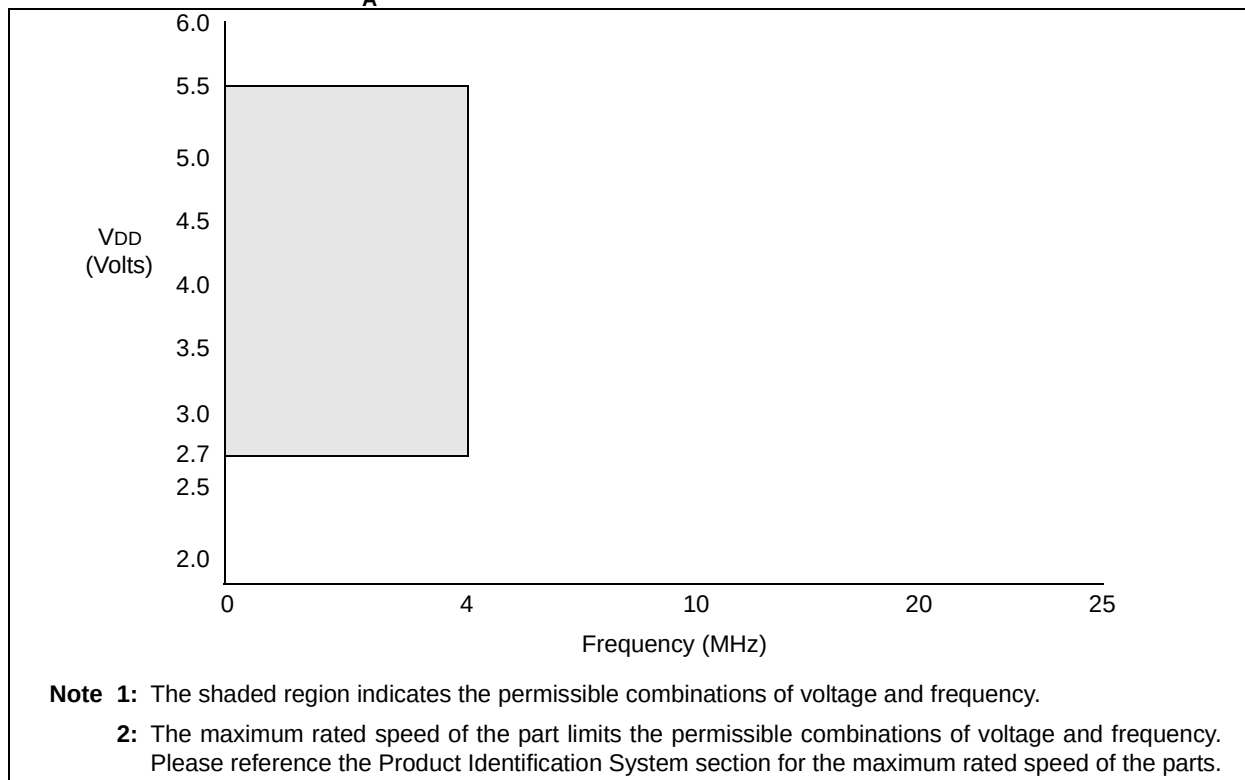


FIGURE 17-4: PIC16LC54C/55A/56A/57C/58B VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A \leq 0^{\circ}\text{C}$



17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial)
 PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
 PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial)
 PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X PIC16LCR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial					
PIC16C5X PIC16CR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial					
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D010	IDD	Supply Current^(2,3)					
		PIC16LC5X	—	0.5	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, XT and RC modes
			—	11	27	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	14	35	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
D010A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC modes
			—	2.6	3.6*	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	4.5	16	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	14	32	μA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Commercial
			—	17	40	μA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

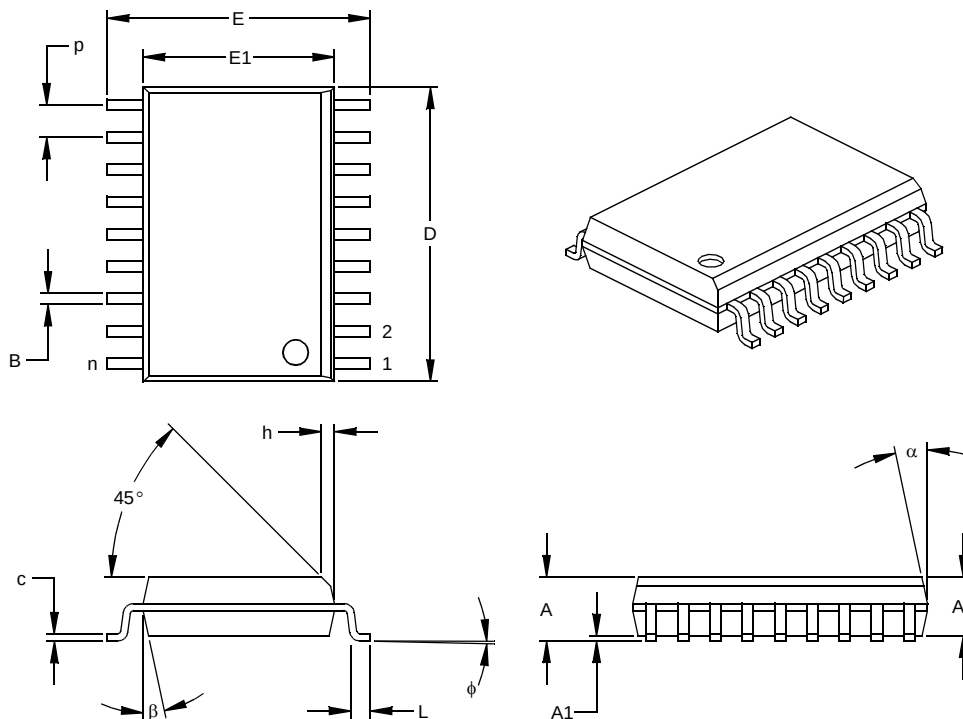
b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula:
 $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

PIC16C5X

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

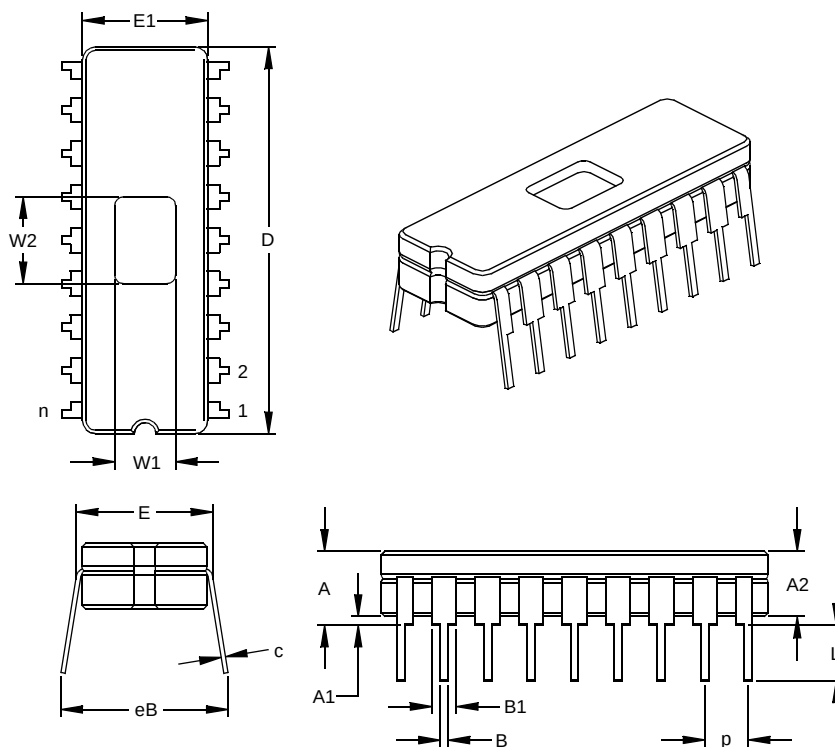
JEDEC Equivalent: MS-013

Drawing No. C04-051

PIC16C5X

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	§ eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter

§ Significant Characteristic

JEDEC Equivalent: MO-036

Drawing No. C04-010

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
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